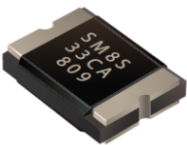


MATERIAL DECLARATION SHEET



Material Number	SM8SF series			
Product Line	Semiconductor Products			
Compliance Date	2018/06/25			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	375	Copper	7440-50-8	97.45	71.94	73.82
				Iron	7439-89-6	2.34	1.73	
				Phosphorus	7723-14-0	0.08	0.06	
				Zinc	7440-66-6	0.13	0.09	
2	Epoxy	Plastic	90	Silicon Dioxides	7631-86-9	76.92	13.63	17.72
				Epoxy	9003-36-5	20.72	3.67	
				Carbon black	1333-86-4	2.36	0.42	
3	Die Attach	Metal	11	Lead ^(Note 2)	7439-92-1	85.9	1.59	2.17
				Tin	7440-31-5	11.7	0.22	
				Silver	7440-22-4	2.3	0.04	
				Bismuth	7440-69-9	0.1	0.00	
4	Dice	Others	29	Silicon	7440-21-3	92.00	5.25	5.70
				Phosphorous	7723-14-0	0.00	0.00	
				Boron	7440-42-8	0.00	0.00	
				Gold	7440-57-5	0.06	0.00	
				Nickel	7440-02-0	1.72	0.10	
				Lead ^(Note 3)	7439-92-1	3.17	0.18	
				Silicon dioxide	7631-86-9	2.50	0.14	
Aluminum oxide	1344-28-1	0.55	0.03					
5	Terminal Plating	Metal	3	Tin	7440-31-5	100	0.59	0.59
		Total weight	508					

This Document was updated on: 2018/6/25

MATERIAL DECLARATION



Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS 7(a) exemption - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
3. RoHS 7(c)-I exemption - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound